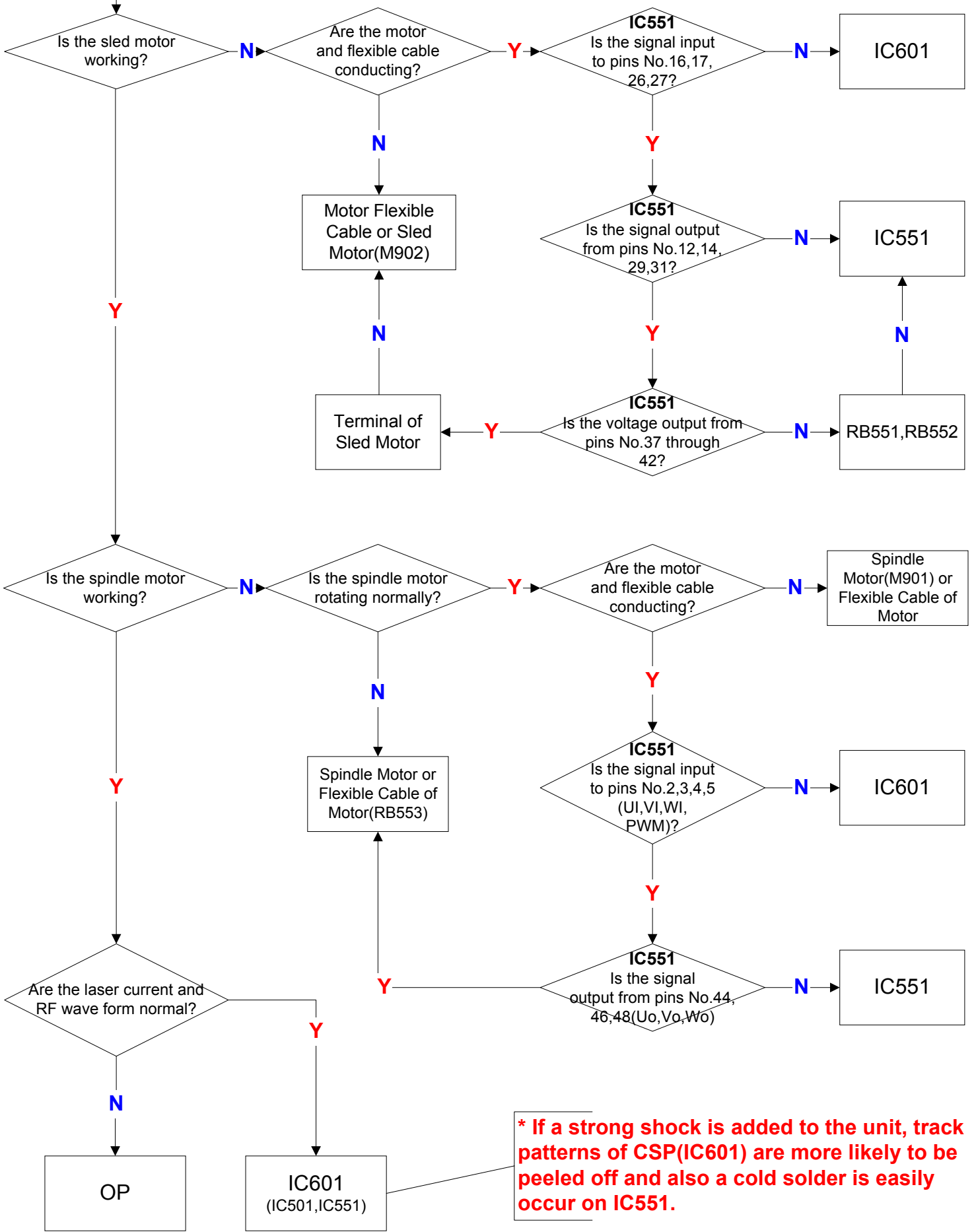
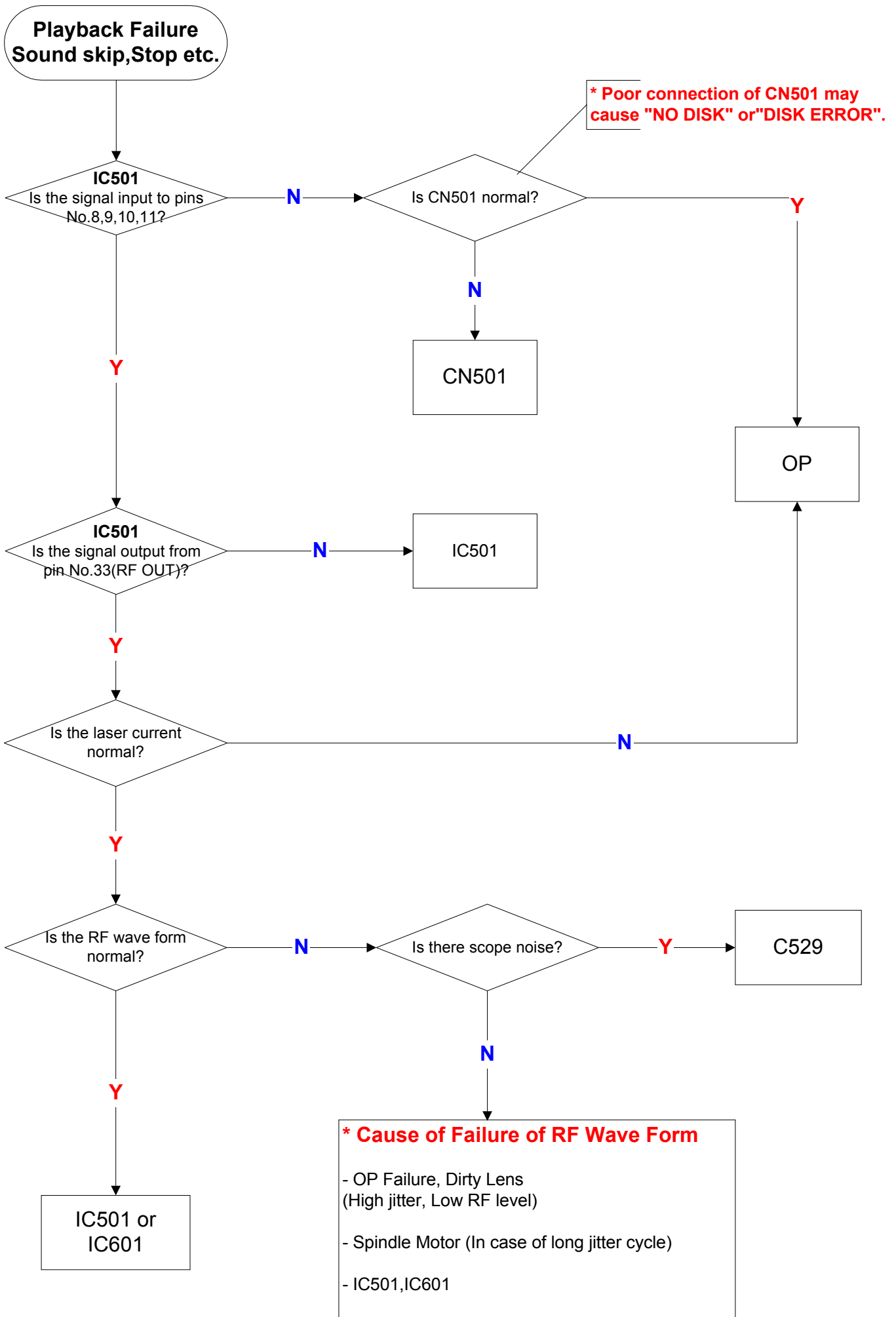
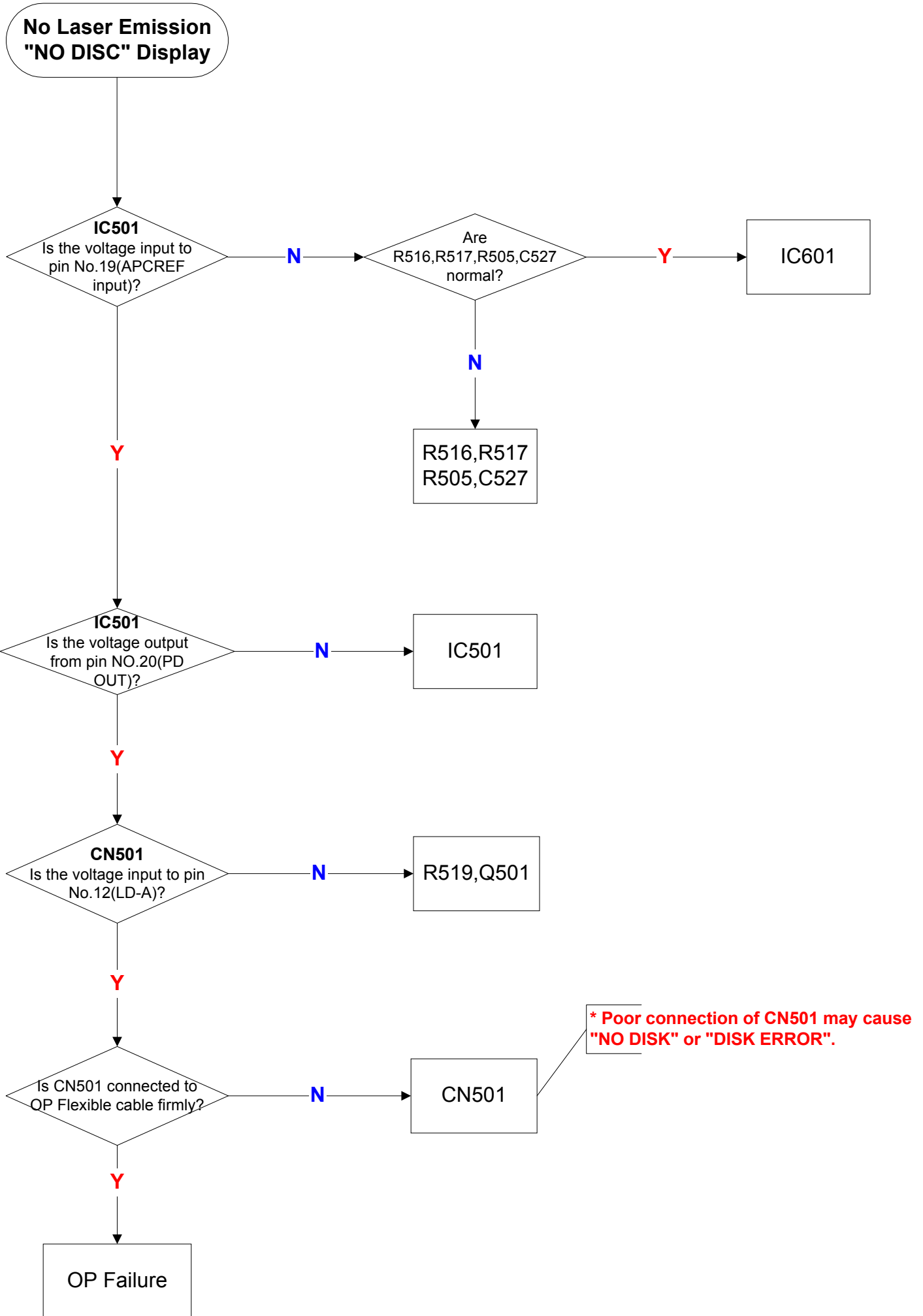


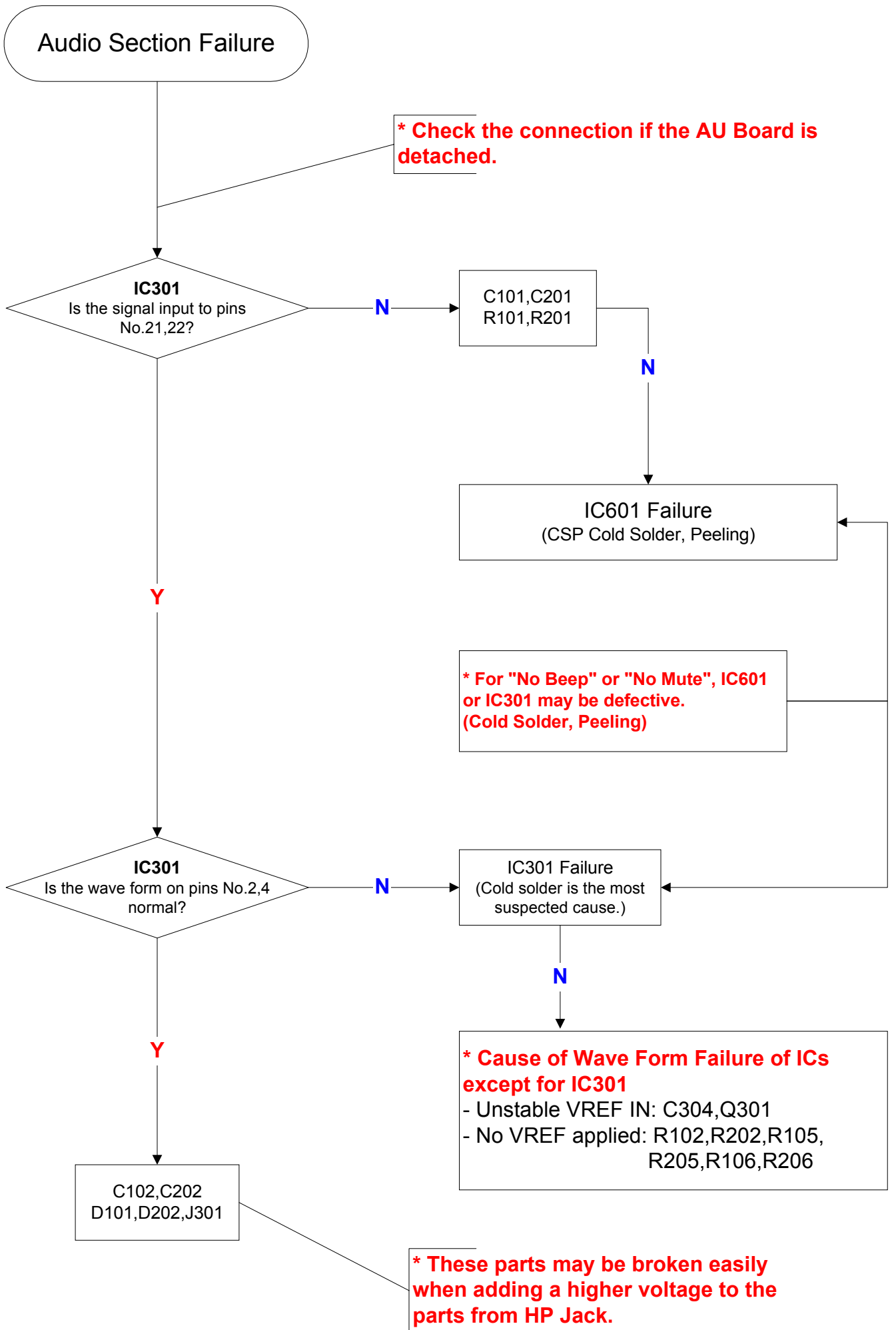
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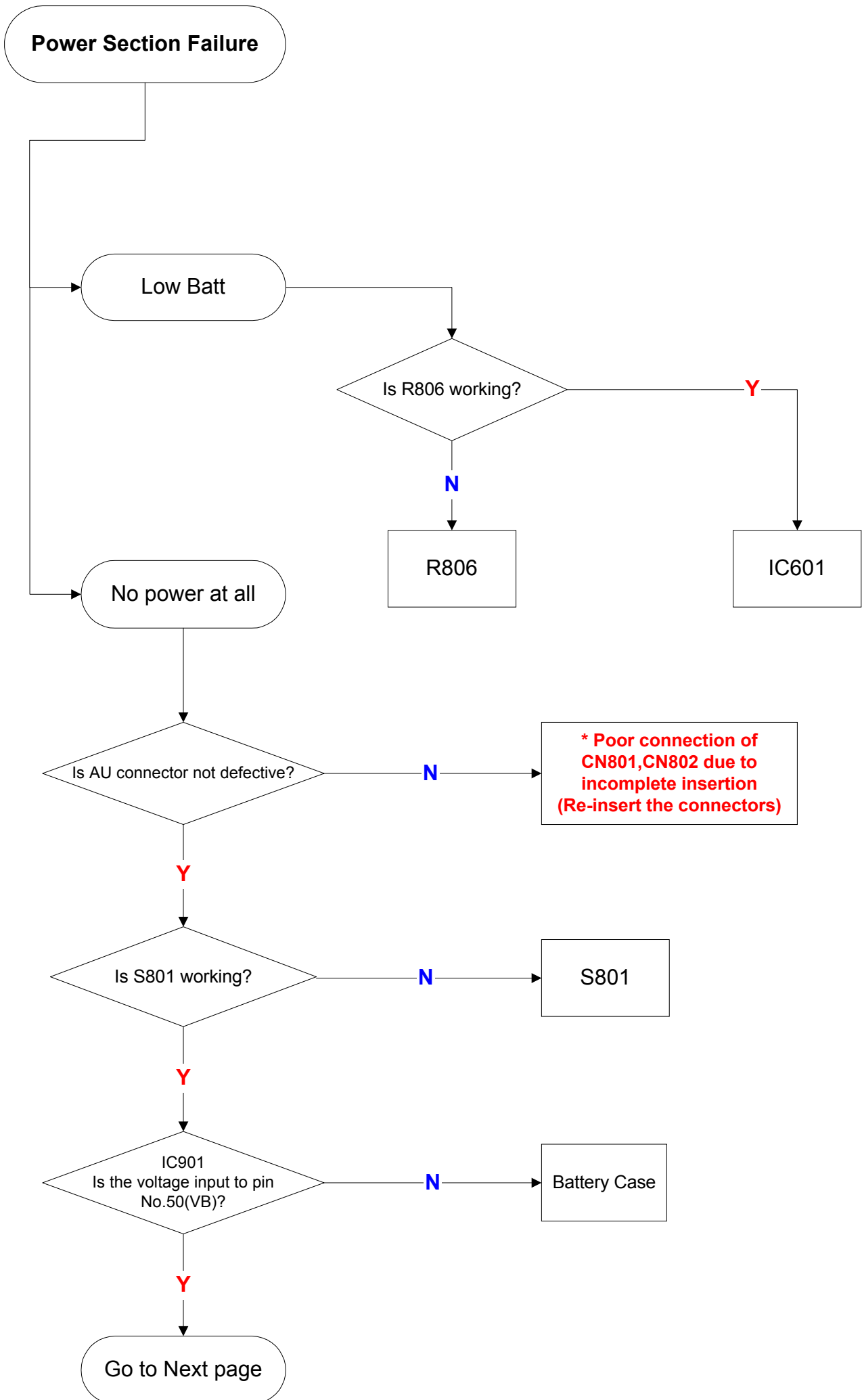


*** If a strong shock is added to the unit, track patterns of CSP(IC601) are more likely to be peeled off and also a cold solder is easily occur on IC551.**









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* Cold solder or peeling of IC901, IC601 are more likely to occur for dropped units.

